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Serial No. 10/782,455
Art Unit: 2831 Examiner: Anton B. Harris
IBM Docket: AUS920031049US1(4037)

1-12 (Cancelled)

13. (Original) A hardware casing for mounting components of a device, comprising:
- a pattern of interconnects applied to an interior surface of the hardware casing, being based upon a topography of the interior surface and capable of transmitting signals, wherein the pattern comprises at least one independent path for transmitting a signal between the components; and
 - mounting sites designed for mounting the components to the interior surface, the mounting sites being coupled with the pattern of interconnects, wherein positioning of the mounting sites is based upon the topography.
14. (Original) The hardware casing of claim 13, further comprising components coupled with the pattern of interconnects via the mounts, the components being independently manufactured to perform distinct functions of the device.
15. (Original) The hardware casing of claim 14, wherein the components comprise an optical switch attached to the hardware casing and communicatively coupled with the pattern of interconnects, wherein the optical switch toggles in response to a change in light sensed by the optical switch.
16. (Original) The hardware casing of claim 14, wherein the components comprise a pressure-sensitive switch coupled with the pattern of interconnects via one of the mounts.
17. (Original) The hardware casing of claim 13, wherein the pattern of interconnects comprises a conductive paint applied directly to the hardware casing, wherein the hardware casing is composed of a substantially non-conductive plastic.

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18. (Original) The hardware casing of claim 17, wherein the hardware casing is composed of a pliable material.
19. (Original) The hardware casing of claim 13, wherein the pattern of interconnects is coupled with the hardware casing via at least one layer of non-conductive laminates.
20. (Original) The hardware casing of claim 13, wherein the pattern of interconnects applied to an interior surface of the hardware casing comprises a layer of metal having portions etched away to reveal the pattern of interconnects.
21. (Original) A system having a device encased by a hardware casing, the system comprising:
 - components, the components being manufactured independently and capable of performing separate functions of the device;
 - a pattern of interconnects applied to an interior surface of the hardware casing, the pattern comprising at least one independent path for transmitting a signal between components independently manufactured and designed to perform separate functions and mounted on the hardware casing, wherein the pattern is based upon a topography of the interior surface;
 - mounts coupling the components to the interior surface, the mounts being coupled with the pattern of interconnects, wherein positioning of the mounts is based upon the topography.
22. (Original) The system of claim 20, wherein the components comprise sensors to sense environmental conditions, the sensors being oriented to face the exterior of the system.
23. (Original) The system of claim 20, wherein the pattern of interconnects resides on a laminate, the laminate being adhered to the interior surface of the hardware casing.

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24. (Original) The system of claim 20, wherein the pattern of interconnects is coupled with a circuit board internal of the device to communicatively couple the components with other components mounted to the circuit board.
25. (New) A method comprising:
transmitting signals via interconnects along at least one independent path on an interior surface of a hardware casing in a pattern based upon a topography of the interior surface to one or more mounting sites; and
receiving the signals by the one or more mounting sites on the interior surface at a position based upon the topography of the interior surface to transmit the signals to at least one component at the one or more mounting sites.
26. (New) The method of claim 25, further comprising coupling the at least one component to the interior surface at one of the mounting sites to mount the at least one component to the hardware casing.
27. (New) The method of claim 26, wherein coupling the at least one component comprises mounting a sensor to the hardware casing to couple the sensor with the interconnects.
28. (New) The method of claim 27, wherein mounting the sensor comprises mounting the sensor to the interior surface of the hardware casing to sense environmental conditions via the hardware casing.
29. (New) The method of claim 26, wherein coupling the at least one component to the interior surface comprises coupling the at least one component to the hardware casing to dissipate heat generated by the at least one component via the hardware casing.
30. (New) The method of claim 26, wherein coupling the at least one component to the interior surface comprises coupling the at least one component with a heat sink

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incorporated into the hardware casing to conduct heat from the at least one component to an environment outside the hardware casing.

31. (New) The method of claim 25, wherein transmitting comprises applying one of the signals to one of the interconnects to conduct the one of the signals via a metal line of the interconnects to the at least one component.
32. (New) The method of claim 31, wherein receiving comprises conductively interconnecting the metal line with the at least one component at the one or more mounting sites.